

WHAT IS CLAIMED IS:

1. An imaging apparatus comprising:
  - a three-dimensional circuit board transmitting virtually no visible
  - 5 light, the three-dimensional circuit board comprising
    - a cylindrical barrel portion, and
    - a bottom portion;
  - a semiconductor imaging device held by the three-dimensional
  - circuit board;
  - 10 an optical system that is held by the barrel portion and directs light
  - to the semiconductor imaging device; and
  - a flexible printed circuit, disposed on the three-dimensional circuit
  - board on a side opposite to the barrel portion, for sending a signal to and
  - receiving a signal from the semiconductor imaging device;
  - 15 wherein a region of the flexible printed circuit facing the
  - semiconductor imaging device has sufficient shielding characteristics in a
  - range sensitive to light reception by the semiconductor imaging device.
2. The imaging apparatus according to claim 1, wherein the
- 20 semiconductor imaging device has a small thickness obtained by grinding its
- back surface.
3. The imaging apparatus according to claim 1, wherein in the region
- of the flexible printed circuit facing the semiconductor imaging device, the
- 25 shielding characteristics against light with a wavelength longer than a
- visible range is higher than that against light in the visible range.
4. The imaging apparatus according to claim 1, wherein a metal foil is
- laminated on the region of the flexible printed circuit facing the
- 30 semiconductor imaging device.
5. The imaging apparatus according to claim 4, wherein the metal foil
- contains aluminum as a main component.
- 35 6. The imaging apparatus according to claim 4, wherein the metal foil
- contains silver or nickel as a main component.